

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT:

[No Variations]

PCB VIEWED FROM TOP SIDE		BOARD #:	TIDA-00753		REV: E1	SUN REU:	Not In VersionControl		
Layer name =	Top Assembly	TID #: TIDA-00753							
PLOT NAME =	Top Assembly Drawing	GENERATED	:	3/23/2016	11:08:39 AN	1	TEXAS INSTRUMENTS		

C28 ZZ3 C26 GZ3 C24 EZ3

COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #:	TIDA-00753	REV: E1	SUN REU:	Not In VersionControl	
Layer Name : Bottom Assembly	TID #: TIDA-00753					
PLOT NAME = Bottom Assembly Drawing	GENERATED :	3/23/2016	11:08:40 AM		TEXAS INSTRUMENTS	

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